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CHEN et al. (43) **Pub. Date: Nov. 17, 2022**(54) **CIRCUIT BOARD, METHOD FOR
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(CN)**(57) **ABSTRACT**

A circuit board includes a circuit substrate, at least one metal pad, and a tin bar corresponding to each of the at least one metal pad. Each of the at least one metal pad is formed on a side of the circuit substrate and is electrically connected to the circuit substrate. A surface of the metal pad facing away from the circuit substrate is recessed toward the circuit substrate to form a recess. The tin bar is received in the recess. A method for manufacturing a circuit board is also provided.

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